



Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32H725IGT6	201T*483XXZ	A	9991	26-07-2023
	Amount	UoM	Unit type	ST ECOPACK Grade
	1650.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	24x24	176	L bend	
Comment	Package : 1T LQFP 176 24x24x1.4 0110489			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	2017*483XXZ				6000000.0	1000000.8
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	13.899	mg	Supplier	die	Silicon (Si)	7440-21-3		13.399	mg	964026	8121
				Supplier	metallization	Aluminium (Al)	7429-90-5		0.059	mg	4245	36
				Supplier	metallization	Copper (Cu)	7440-50-8		0.186	mg	13382	113
				Supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	72	1
				Supplier	metallization	Tantalum (Ta)	7440-25-7		0.030	mg	2158	18
				Supplier	metallization	Titanium (Ti)	7440-32-6		0.005	mg	360	3
				Supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	72	1
Leadframe (C7025 + Ag + R970)	Copper & its alloys	425.000	mg	Supplier	Passivation	Silicon Oxide	7631-86-9		0.218	mg	15685	132
				Supplier	Leadframe	Copper(Cu)	7440-50-8		385.178	mg	906300	233441
				Supplier	Leadframe	Nickle ( Ni )	7440-02-0		12.920	mg	30400	7830
				Supplier	Leadframe	Silicon ( Si )	7440-21-3		4.845	mg	11400	2936
				Supplier	Leadframe	Magnesium ( Mg )	7439-95-4		1.233	mg	2900	747
				Supplier	Leadframe	Silver(Ag)	7440-22-4		14.875	mg	35000	9015
				Supplier	Leadframe	Polymide	Proprietary		2.380	mg	5600	1442
				Supplier	Leadframe	Poly-ethylene-terephthalate	25038-59-6		1.785	mg	4200	1082
				Supplier	Leadframe	NBR	9003-18-3		0.595	mg	1400	361
				Supplier	Leadframe	Bismaleimide	79922-55-7		0.595	mg	1400	361
				Supplier	Leadframe	Phenol resin	28453-20-5		0.595	mg	1400	361
				Glue epoxy (EN4900G)	Precious metals	2.800	mg	Supplier	Glue or tape	Silver	7440-22-4	
Supplier	Glue or tape	Cresol Novolac Epoxy Resins	Proprietary						0.070	mg	25000	42
Supplier	Glue or tape	Bisphenol A Diacrylate	Proprietary						0.238	mg	85000	144
Supplier	Glue or tape	Dicyclopentenyl group containing Acrylate	Proprietary						0.154	mg	55000	93
Supplier	Glue or tape	Butadiene copolymer	Proprietary						0.028	mg	10000	17
Supplier	Glue or tape	Polybutadiene epoxidized derivative	Proprietary						0.154	mg	55000	93
Supplier	Glue or tape	Peroxy Ketals	Proprietary						0.014	mg	5000	8
Supplier	Glue or tape	Substitutedalkoxyalkyl trimethoxysilane	Proprietary						0.014	mg	5000	8
Bonding wire (Cu)	Precious metals	2.100	mg	Supplier	Bonding wire	Copper	7440-50-8		2.028	mg	965500	1229
				Supplier	Bonding wire	Palladium	7440-05-3		0.065	mg	31000	39
				Supplier	Bonding wire	Gold	7440-57-5		0.007	mg	3500	4
Encapsulation (EME-G6315H)	M-011 Other inorganic materials	1190.305	mg	Supplier	Molding Compound	2,2'-(3,3',5,5'-Tetramethyl-(1,1'-biphenyl))-4,4'	85954-11-6		47.612	mg	40000	28856
				Supplier	Molding Compound	Epoxy resin	Proprietary		23.806	mg	20000	14428
				Supplier	Molding Compound	Phenol Resin	Proprietary		89.273	mg	75000	54105
				Supplier	Molding Compound	Silica(Amorphous) A	60676-86-0		844.521	mg	709500	511831
				Supplier	Molding Compound	Silica(Amorphous) B	7631-86-9		178.546	mg	150000	108210
External Plating (Sn)	M-011 Other inorganic materials	15.895	mg	Supplier	Molding Compound	Carbon black	1333-86-4		6.547	mg	5500	3968
				Supplier	Matte Sn	Tin (Sn)	7440-31-5		15.893	mg	999900	9632
				Supplier	Matte Sn	Impurities	-		0.002	mg	100	1